

Title (en)  
APPARATUS FOR PLATING CYLINDER

Title (de)  
VORRICHTUNG ZUR PLATTIERUNG EINES ZYLINDERS

Title (fr)  
APPAREIL DE PLACAGE DE CYLINDRE

Publication  
**EP 2623646 A1 20130807 (EN)**

Application  
**EP 11829066 A 20110927**

Priority  
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• JP 2011071960 W 20110927

Abstract (en)  
Provided is a plating apparatus for a cylinder, which is capable of extending service life of the entire apparatus in a technology of plating a cylinder, eliminating hardness nonuniformity of a plating layer on a cylinder surface by achieving a uniform hardness, and suppressing oxidation of a tip of chuck means. The plating apparatus for a cylinder includes: a plating bath to be filled with a plating solution; chuck means for holding a long cylinder at both ends in a longitudinal direction so as to be rotated and energized, and accommodating the long cylinder in the plating bath; and a pair of opposed insoluble electrodes which is vertically installed so as to face both side surfaces of the long cylinder in the plating bath, and is supplied with a predetermined current. The chuck means includes thermal cooling means, and the thermal cooling means includes a cooling medium and causes the cooling medium to circulate to cool a cylinder holding section of the chuck means so that heat accumulation in the long cylinder, in particular, a cylinder end portion and the cylinder holding section of the chuck means is eliminated.

IPC 8 full level  
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